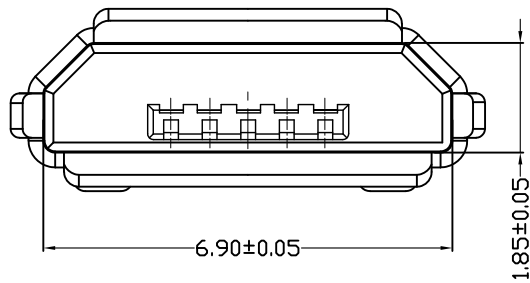
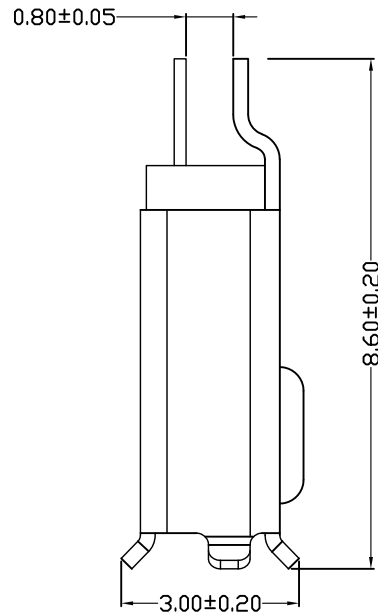
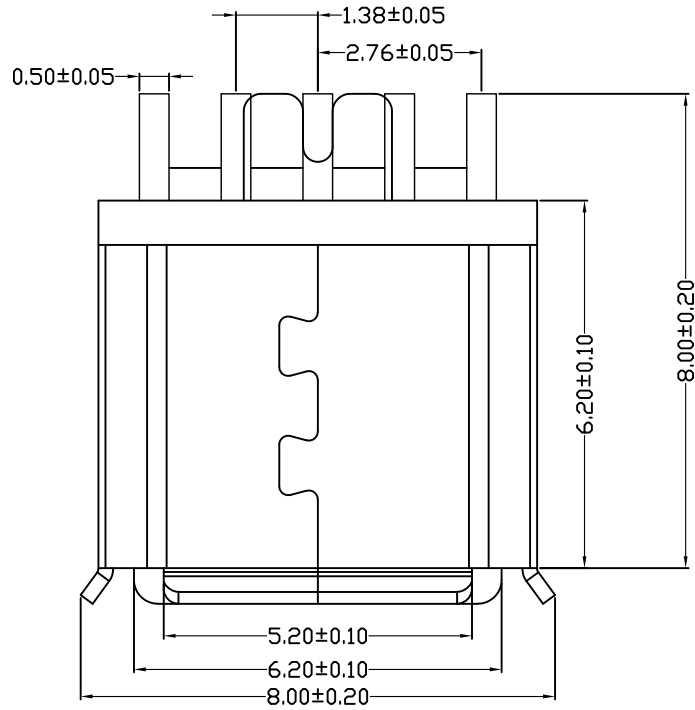


|      |      |    |    |
|------|------|----|----|
| 修改序号 | 修改说明 | 签名 | 日期 |
| A/0  |      |    |    |



Note:

1. Material:

- 1.1 Housing: High temperature thermoplastic with g.f, UL94v-0
- 1.2 Contact: copper alloy,  $t=0.20\text{mm}$
- 1.3 Shell: Copper alloy or SUS,  $t=0.25\text{mm}$

2. Specification:

- 2.1 Current rating: 1A Max
- 2.2 Dielectric withstanding voltage: 100V(AC) for 1 min.
- 2.3 Contact resistance:  $40\text{m}\Omega$  Max.
- 2.4 Insulation resistance:  $100\text{M}\Omega$  min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf  
Min. 0.81~2.05 Kgf Min.  
after 3000 or 10,000 insertion/  
extration cycles
- 2.7 Temperature range:  $-30^{\circ}\text{C}\sim 80^{\circ}\text{C}$

|      |                    |
|------|--------------------|
| 尺寸   | 允许公差               |
| .X   | $\pm 0.50$         |
| .X   | $\pm 0.20$         |
| .XX  | $\pm 0.10$         |
| .XXX | $\pm 0.03$         |
| 角度   | $\pm 1.00^{\circ}$ |

深圳市创勤电子有限公司  
SHENZHEN CHUANGQIN ELECTRONICS CO., LTD.

|       |         |                          |                   |
|-------|---------|--------------------------|-------------------|
| 图纸类型  |         | 图纸名称:                    |                   |
| 产品工程图 |         | MICRO USB 5P BF夹板0.8凸包无孔 |                   |
| 设计    | LIN YUN | 2011.05.22               | 产品料号              |
| 审核    | LIJY    |                          | CQ028-MCJB0508100 |
| 视图    |         | 版号: A/0                  |                   |